



QSBT40

QUAD DATA LINE SCHOTTKY BUS TERMINATOR

Features

Low Forward Voltage Drop

IEC61000-4-5 (Lightning) Class 3

- Fast Switching
- Very High Density
- Ultra-Small Surface Mount Package PN Junction Guard Ring for Transient and ESD Protection
- Provide Transient Protection for High-Speed Data Lines in Accordance With: IEC61000-4-2 (ESD) 15kV (Air), 8kV (Contact) IEC61000-4-4 (EFT) 80A (tp = 5/50 ns)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Notes 3 & 4)

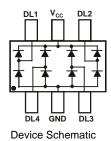
Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)





Top View



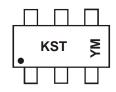
Ordering Information (Note 5)

Part Number	Case	Packaging
QSBT40-7-F	SOT363	3000/Tape & Reel
QSBT40-13-F	SOT363	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
- 5. For packaging details, go to our website at http://www.diodes.com.

Marking Information



KST = Product Type Marking Code YM = Date Code Marking Y = Year (ex: N = 2002) M = Month (ex: 9 = September)

Date Code Key

Year	2001	2002	2003	2004		2011	2012	2013	2014	2015	2016	2017
Code	М	N	Р	R		Υ	Z	Α	В	С	D	Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _R WM V _R	30	V
Forward Continuous Current (Note 6)	I _{FM}	200	mA
Non-Repetitive Peak Forward Surge Current @ t < 1.0s	I _{FSM}	600	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{ heta JA}$	625	°C/W
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T _{STG}	-65 to +125	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	30			٧	$I_R = 100 \mu A$
Forward Voltage	V _F	_	l	280 350 450 550 1000	mV	$I_F = 0.1 \text{mA}, \text{ tp} < 300 \mu \text{S}$ $I_F = 1.0 \text{mA}, \text{ tp} < 300 \mu \text{S}$ $I_F = 10 \text{mA}, \text{ tp} < 300 \mu \text{S}$ $I_F = 30 \text{mA}, \text{ tp} < 300 \mu \text{S}$ $I_F = 100 \text{mA}, \text{ tp} < 300 \mu \text{S}$
Reverse Current (Note 7)	I_R	_		2	μΑ	$V_R = 25V$
Total Capacitance	C _T	_	10.0 6.5		pF	$V_R = 0$, $f = 1.0MHz$ (Note 8) $V_R = 0$, $f = 1.0MH_z$ (Note 9)
Reverse Recovery Time	t _{rr}	_		5.0	ns	$\begin{split} I_F &= I_R = 10 \text{mA}, \\ I_{rr} &= 0.1 \text{ x } I_R, \ R_L = 100 \Omega \end{split}$

Notes:

- 6. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. At $V_R = 0V$, DL(X) to V_{CC} or GND.
- 9. At $V_R = 0V$, between Data Lines (e.g., DL1 and DL4).

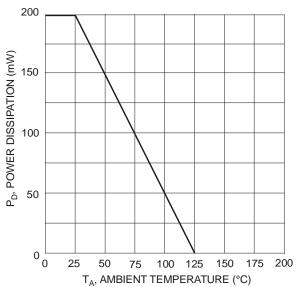
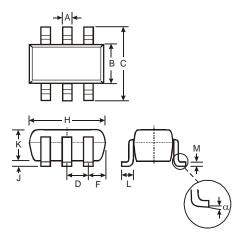


Fig. 1 Max Power Dissipation vs. Ambient Temperature



Package Outline Dimensions

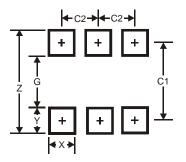
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT363						
Dim	Min	Max	Тур				
Α	0.10	0.30	0.25				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D		0.65 Ty	р				
F	0.40	0.45	0.425				
Н	1.80	2.20	2.15				
J	0	0.10	0.05				
K	0.90	1.00	1.00				
L	0.25	0.40	0.30				
M	0.10	0.22	0.11				
α	0°	8°	-				
All Dimensions in mm							

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Υ	0.6
C1	1.9
C2	0.65



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